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Kind regards,

Team Nexperia

# PEMB10; PUMB10

PNP/PNP resistor-equipped transistors;  
R1 = 2.2 k $\Omega$ , R2 = 47 k $\Omega$

Rev. 3 — 3 January 2012

Product data sheet

## 1. Product profile

### 1.1 General description

PNP/PNP Resistor-Equipped Transistors (RET) in Surface-Mounted Device (SMD) plastic packages.

Table 1. Product overview

Type number	Package		NPN/PNP complement	NPN/NPN complement	Package configuration
	NXP	JEITA			
PEMB10	SOT666	-	PEMD10	PEMH10	ultra small and flat lead
PUMB10	SOT363	SC-88	PUMD10	PUMH10	very small

### 1.2 Features and benefits

- 100 mA output current capability
- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduces pick and place costs
- AEC-Q101 qualified

### 1.3 Applications

- Low current peripheral driver
- Control of IC inputs
- Replaces general-purpose transistors in digital applications

### 1.4 Quick reference data

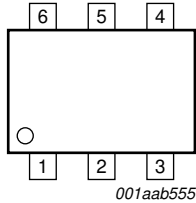
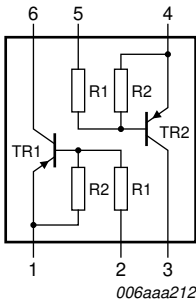
Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-	-50	V
I <sub>O</sub>	output current		-	-	-100	mA
R1	bias resistor 1 (input)		1.54	2.20	2.86	k $\Omega$
R2/R1	bias resistor ratio		17	21	26	



## 2. Pinning information

**Table 3. Pinning**

Pin	Description	Simplified outline	Graphic symbol
1	GND (emitter) TR1		
2	input (base) TR1		
3	output (collector) TR2		
4	GND (emitter) TR2		
5	input (base) TR2		
6	output (collector) TR1		

## 3. Ordering information

**Table 4. Ordering information**

Type number	Package		
	Name	Description	Version
PEMB10	-	plastic surface-mounted package; 6 leads	SOT666
PUMB10	SC-88	plastic surface-mounted package; 6 leads	SOT363

## 4. Marking

**Table 5. Marking codes**

Type number	Marking code <sup>[1]</sup>
PEMB10	Z5
PUMB10	B*0

[1] \* = placeholder for manufacturing site code.

## 5. Limiting values

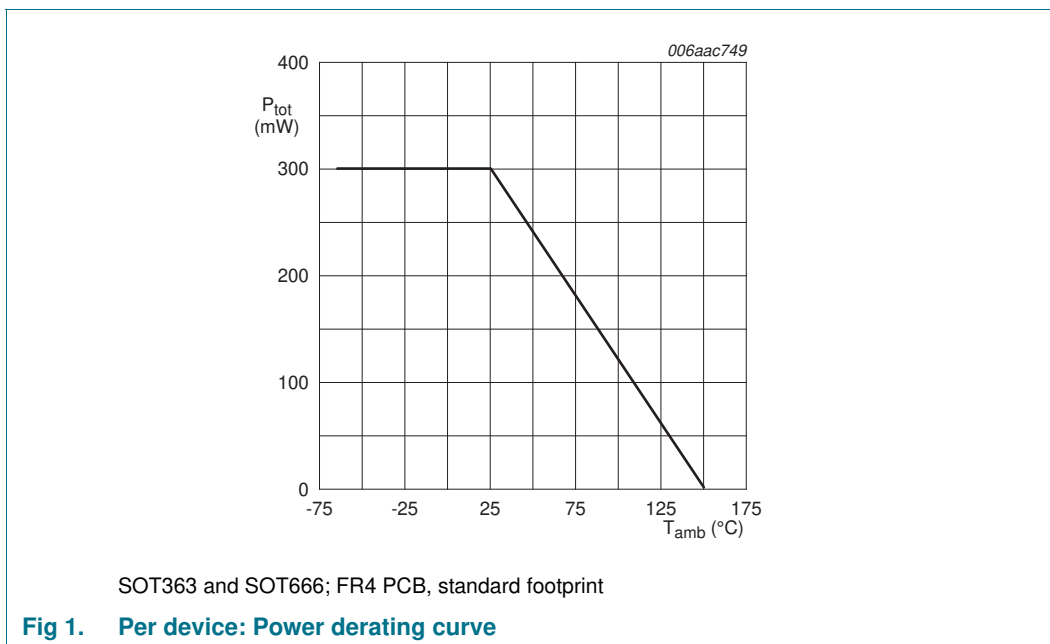
**Table 6. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit	
<b>Per transistor</b>						
V <sub>CBO</sub>	collector-base voltage	open emitter	-	-50	V	
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-50	V	
V <sub>EBO</sub>	emitter-base voltage	open collector	-	-5	V	
V <sub>I</sub>	input voltage					
	positive		-	+5	V	
	negative		-	-12	V	
I <sub>O</sub>	output current		-	-100	mA	
I <sub>CM</sub>	peak collector current		-	-100	mA	
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1]			
	PEMB10 (SOT666)		[2]	-	200	mW
	PUMB10 (SOT363)			-	200	mW
<b>Per device</b>						
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1]			
	PEMB10 (SOT666)		[2]	-	300	mW
	PUMB10 (SOT363)			-	300	mW
T <sub>j</sub>	junction temperature		-	150	°C	
T <sub>amb</sub>	ambient temperature		-65	+150	°C	
T <sub>stg</sub>	storage temperature		-65	+150	°C	

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.



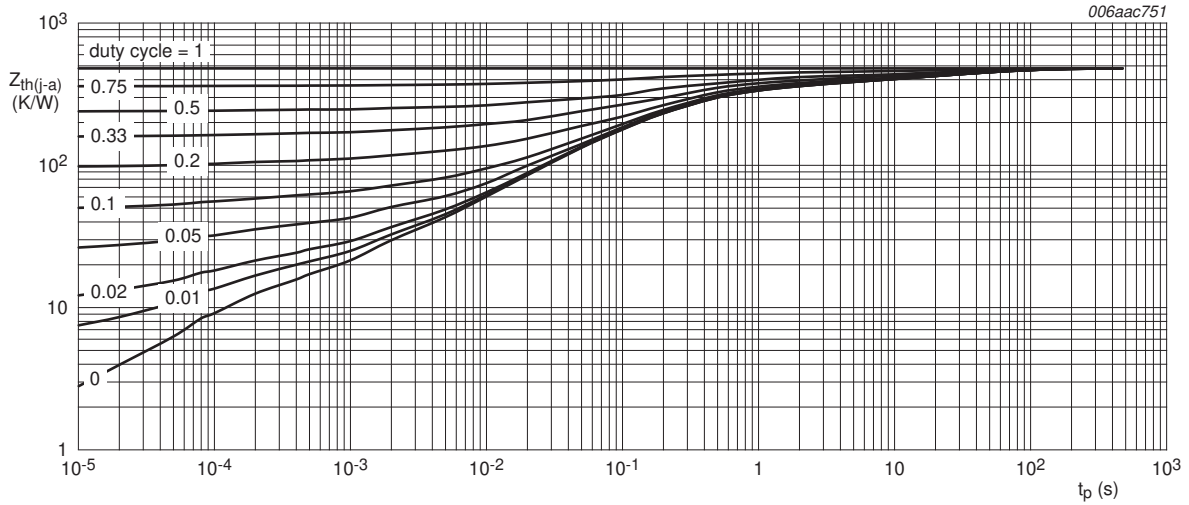
## 6. Thermal characteristics

**Table 7. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]			
	PEMB10 (SOT666)		[2]	-	625	K/W
	PUMB10 (SOT363)		-	-	625	K/W
<b>Per device</b>						
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]			
	PEMB10 (SOT666)		[2]	-	417	K/W
	PUMB10 (SOT363)		-	-	417	K/W

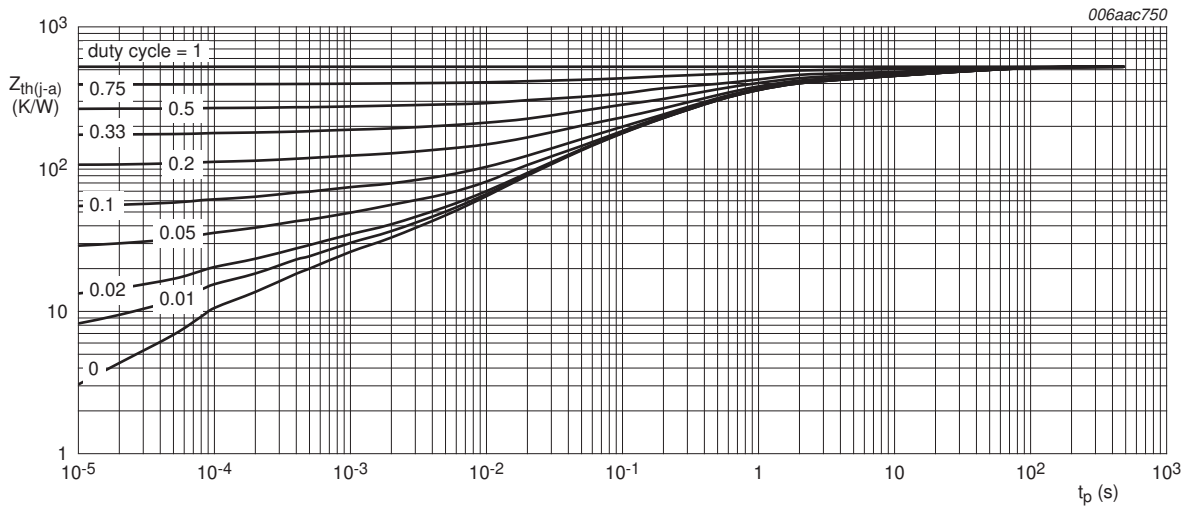
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.



FR4 PCB, standard footprint

**Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration for PEMB10 (SOT666); typical values**



FR4 PCB, standard footprint

**Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration for PUMB10 (SOT363); typical values**

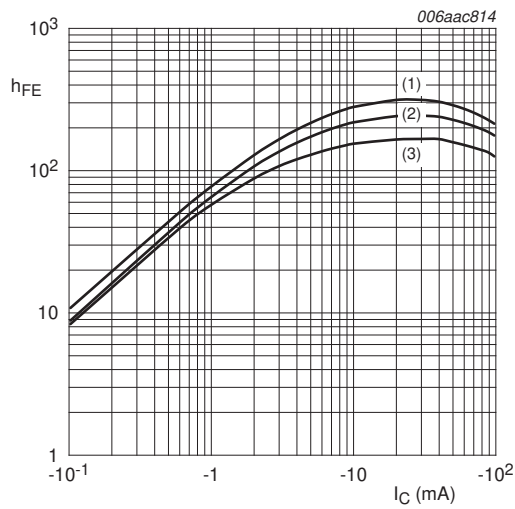
**7. Characteristics**

**Table 8. Characteristics**  
*T<sub>amb</sub> = 25 °C unless otherwise specified.*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Per transistor</b>						
I <sub>CBO</sub>	collector-base cut-off current	V <sub>CB</sub> = -50 V; I <sub>E</sub> = 0 A	-	-	-100	nA
I <sub>CEO</sub>	collector-emitter cut-off current	V <sub>CE</sub> = -30 V; I <sub>B</sub> = 0 A	-	-	-100	nA
		V <sub>CE</sub> = -30 V; I <sub>B</sub> = 0 A; T <sub>j</sub> = 150 °C	-	-	-5	μA
I <sub>EBO</sub>	emitter-base cut-off current	V <sub>EB</sub> = -5 V; I <sub>C</sub> = 0 A	-	-	-180	μA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = -5 V; I <sub>C</sub> = -10 mA	100	-	-	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = -5 mA; I <sub>B</sub> = -0.25 mA	-	-	-100	mV
V <sub>I(off)</sub>	off-state input voltage	V <sub>CE</sub> = -5 V; I <sub>C</sub> = -100 μA	-	-0.6	-0.5	V
V <sub>I(on)</sub>	on-state input voltage	V <sub>CE</sub> = -0.3 V; I <sub>C</sub> = -5 mA	-1.1	-0.75	-	V
R1	bias resistor 1 (input)		1.54	2.20	2.86	kΩ
R2/R1	bias resistor ratio		17	21	26	
C <sub>c</sub>	collector capacitance	V <sub>CB</sub> = -10 V; I <sub>E</sub> = i <sub>e</sub> = 0 A; f = 1 MHz	-	-	3	pF
f <sub>T</sub>	transition frequency	V <sub>CB</sub> = -5 V; I <sub>C</sub> = -10 mA; f = 100 MHz	[1]	-	180	MHz

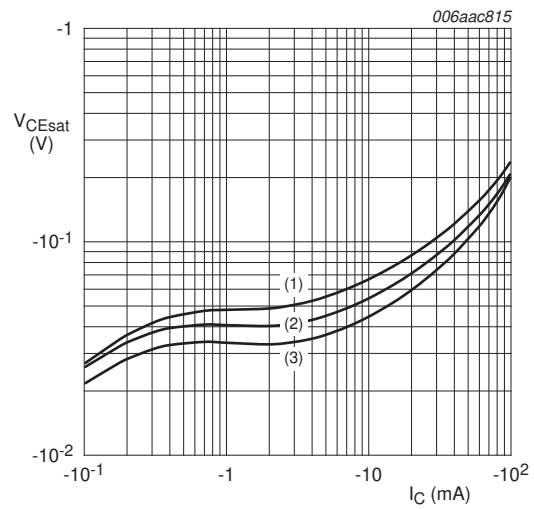
[1] Characteristics of built-in transistor.





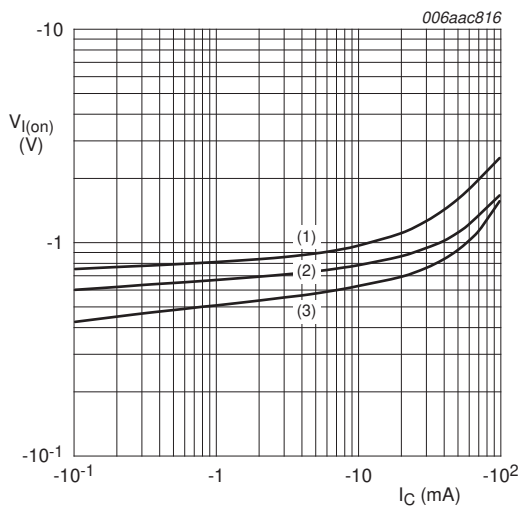
$V_{CE} = -5 \text{ V}$   
 (1)  $T_{amb} = 100 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -40 \text{ }^\circ\text{C}$

**Fig 4. DC current gain as a function of collector current; typical values**



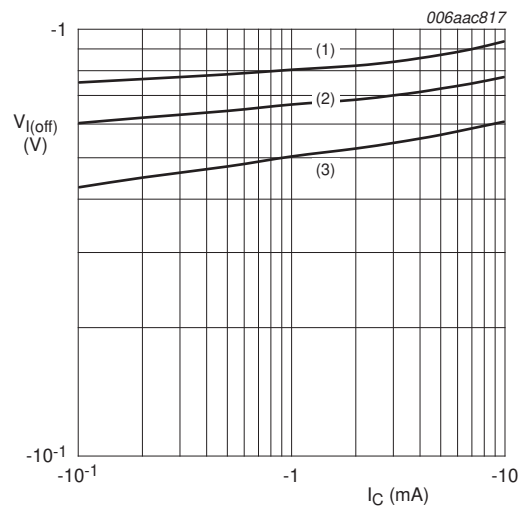
$I_C/I_B = 20$   
 (1)  $T_{amb} = 100 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = -40 \text{ }^\circ\text{C}$

**Fig 5. Collector-emitter saturation voltage as a function of collector current; typical values**



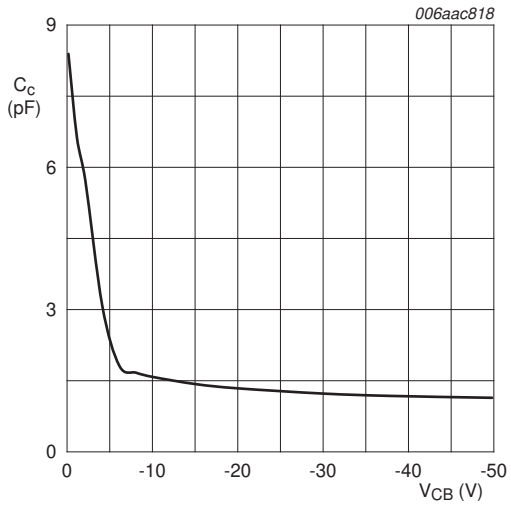
$V_{CE} = -0.3 \text{ V}$   
 (1)  $T_{amb} = -40 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100 \text{ }^\circ\text{C}$

**Fig 6. On-state input voltage as a function of collector current; typical values**



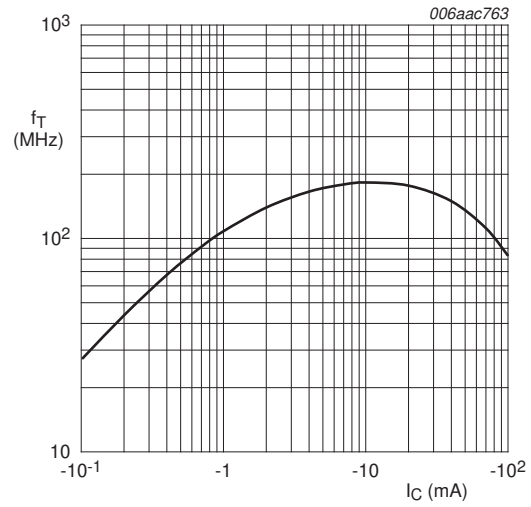
$V_{CE} = -5 \text{ V}$   
 (1)  $T_{amb} = -40 \text{ }^\circ\text{C}$   
 (2)  $T_{amb} = 25 \text{ }^\circ\text{C}$   
 (3)  $T_{amb} = 100 \text{ }^\circ\text{C}$

**Fig 7. Off-state input voltage as a function of collector current; typical values**



$f = 1 \text{ MHz}; T_{amb} = 25 \text{ }^\circ\text{C}$

**Fig 8. Collector capacitance as a function of collector-base voltage; typical values**



$V_{CE} = -5 \text{ V}; T_{amb} = 25 \text{ }^\circ\text{C}$

**Fig 9. Transition frequency as a function of collector current; typical values of built-in transistor**

## 8. Test information

### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

## 9. Package outline

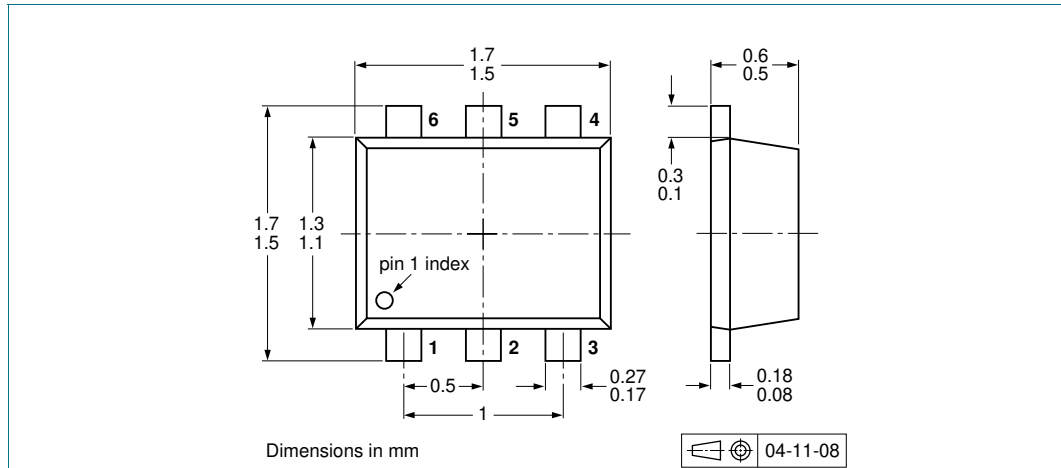


Fig 10. Package outline PEMB10 (SOT666)

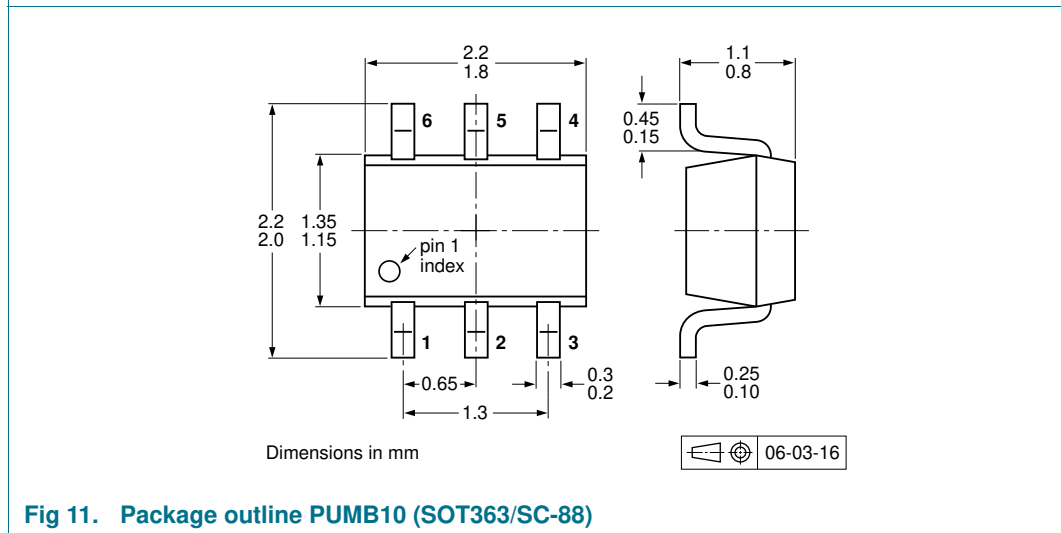


Fig 11. Package outline PUMB10 (SOT363/SC-88)

## 10. Packing information

**Table 9. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

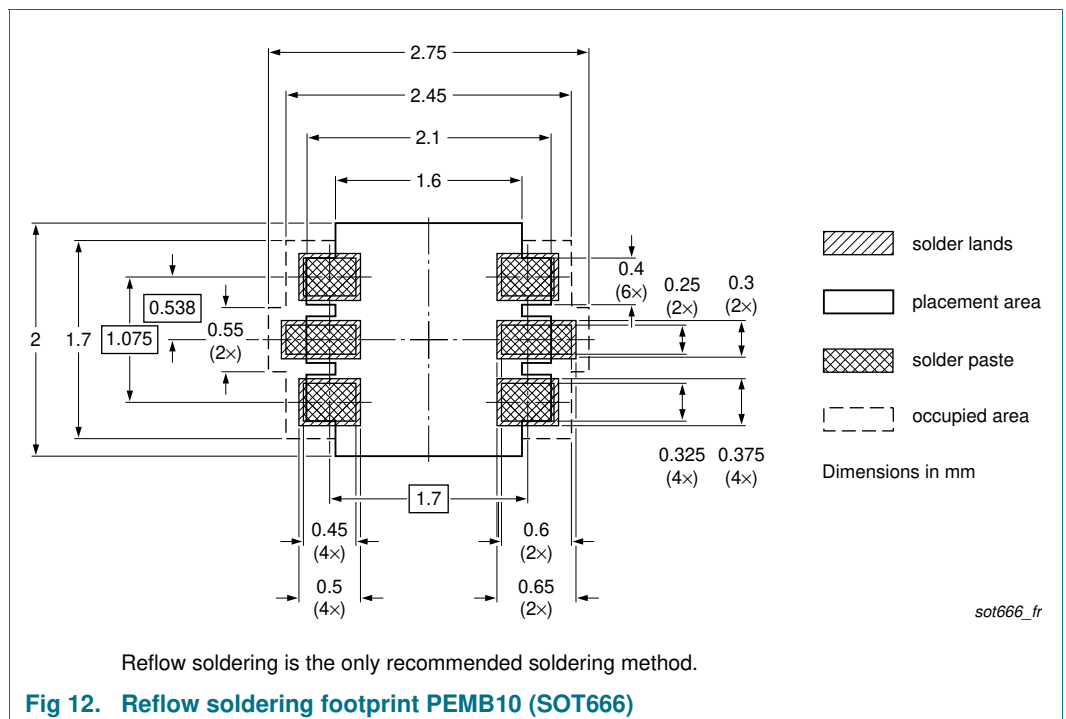
Type number	Package	Description	Packing quantity			
			3000	4000	8000	10000
PEMB10	SOT666	2 mm pitch, 8 mm tape and reel	-	-	-315	-
		4 mm pitch, 8 mm tape and reel	-	-115	-	-
PUMB10	SOT363	4 mm pitch, 8 mm tape and reel; T1 <sup>[2]</sup>	-115	-	-	-135
		4 mm pitch, 8 mm tape and reel; T2 <sup>[3]</sup>	-125	-	-	-165

[1] For further information and the availability of packing methods, see [Section 14](#).

[2] T1: normal taping

[3] T2: reverse taping

## 11. Soldering



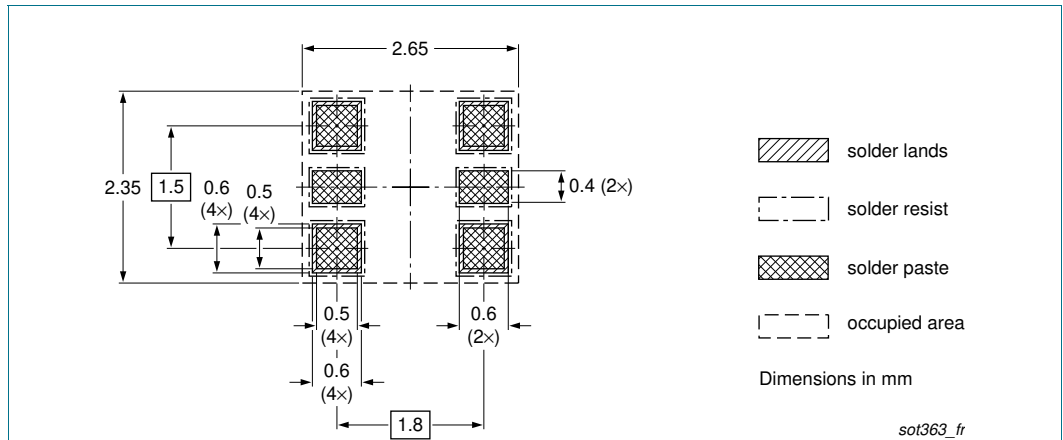


Fig 13. Reflow soldering footprint PUMB10 (SOT363/SC-88)

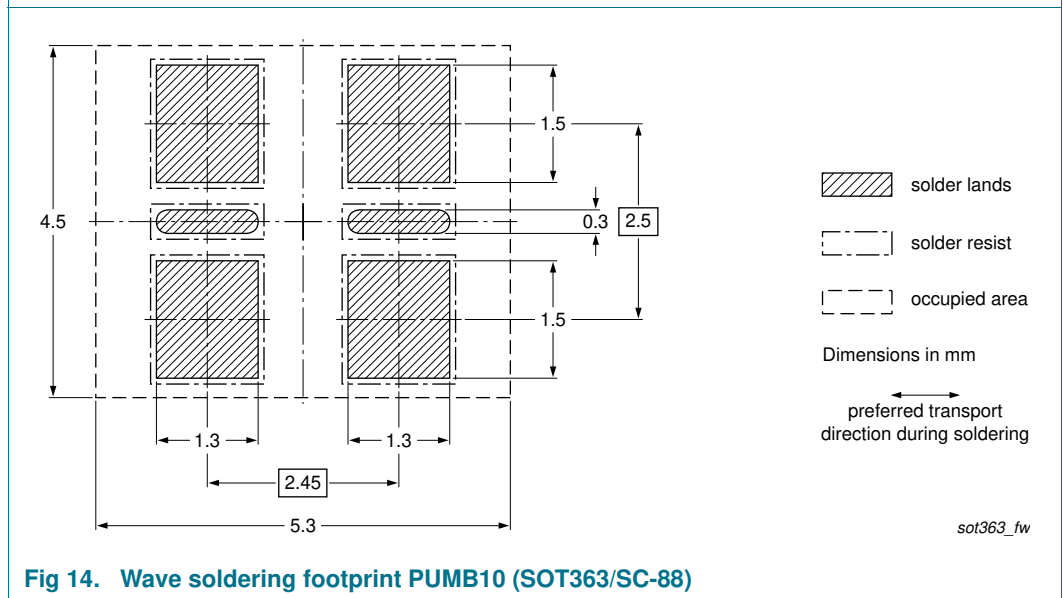


Fig 14. Wave soldering footprint PUMB10 (SOT363/SC-88)

## 12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PEMB10_PUMB10 v.3	20120103	Product data sheet	-	PEMB10_PUMB10 v.2
Modifications:	<ul style="list-style-type: none"> <li>The format of this document has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li><a href="#">Section 1 "Product profile"</a>: updated</li> <li><a href="#">Section 4 "Marking"</a>: updated</li> <li><a href="#">Table 7 "Thermal characteristics"</a>: updated according to the latest measurements</li> <li><a href="#">Table 8 "Characteristics"</a>: I<sub>CEO</sub> updated according to the latest measurements, f<sub>T</sub> added, V<sub>i(off)</sub> redefined to V<sub>I(off)</sub> off-state input voltage, V<sub>i(on)</sub> redefined to V<sub>I(on)</sub> on-state input voltage.</li> <li><a href="#">Figure 1</a> to <a href="#">9</a>: added</li> <li><a href="#">Section 8 "Test information"</a>: added</li> <li><a href="#">Figure 10</a> and <a href="#">11</a>: replaced by minimized package outline drawings</li> <li><a href="#">Section 10 "Packing information"</a>: added</li> <li><a href="#">Section 11 "Soldering"</a>: added</li> <li><a href="#">Section 13 "Legal information"</a>: updated</li> </ul>			
PEMB10_PUMB10 v.2	20031003	Product data sheet	-	PEMB10 v.1
PEMB10 v.1	20010914	Preliminary specification	-	-

## 13. Legal information

### 13.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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